

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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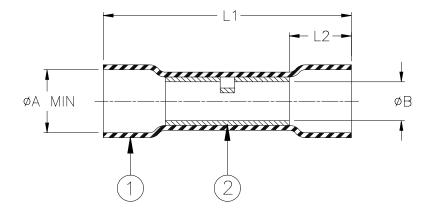
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SPECIFICATION CONTROL DRAWING



Product Revision				Size Range	L1 ±1.5	L2	øA*		øB	Wire Strip
Product		Color	Marking	mm ²	$(L1 \pm 0.06)$	min	(a)	(b)	min	Length
Name				(AWG)			min	max		Nom.
C-203-01	A	Red	PolyCrimp 22-18	0.5 - 1.0	31.5	5.00	3.70	1.14	1.47	6 to 10
				(22 - 18)	(1.24)	(0.20)	(0.146)	(0.045)	(0.058)	(1/4 to 3/8)
C-203-02	A	Blue	PolyCrimp 16-14	1.5 - 2.5	31.5	5.0	4.60	2.00	2.33	6 to 10
				(16 - 14)	(1.24)	(0.20)	(0.181)	(0.080)	(0.092)	(1/4 to 3/8)
C-203-03	A	Yellow	PolyCrimp 12-10	3.0 - 6.0	37.5	10.0	6.50	2.54	3.50	10 to 13
				(12 - 10)	(1.48)	(0.39)	(0.255)	(0.100)	(0.138)	(3/8 to 1/2)

MATERIALS

- 1. INSULATION SLEEVE: Heat-shrinkable, radiation cross-linked polyethylene with a polyethylene-based hot-melt adhesive liner. Color per table.
- 2. CRIMP SPLICE: Tin-plated copper alloy.

BASE METAL: Copper Alloy C110 or better. PLATING: Tin plated per MIL-T-10727, Type 1.

APPLICATION

- 1. These parts may be used to obtain a one-to-one in-line (butt) splice in wires meeting the size range and diameter restraints specified herein and having a temperature rating of not less than 85°C.
- 2. *øA: (a) Minimum diameter as received: Wire insulation diameter must be less than this value.
 - (b) Maximum diameter after recovery: Wire insulation diameter must be larger than this value to obtain an environment resistant splice.
- 3. Wires are to be stripped per table, inserted into opposite ends of the crimp barrel, crimped with a Raychem AD-1522 tool (or equivalent). The sleeve must be heated along its whole length until the crimp marks are gone and the ends of the sleeve recover onto the wires.
- 4. Spliced assemblies will meet the requirements of Raychem Specification D-5203.

Electronics RA		YCHEM	300 Con	ectronics Corporation stitutional Drive ark, CA 94025 USA	POLY CRIMP SPLICE					
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]					DOCUMENT NO.: C-203-0X					
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	Tyco Electronics reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.			DOC. ISSUE:			DATE: 25-Apr-03		
PREPARED BY: mfo	ronda	REPLACES: D010534		DCR NUMBER: D030243	PROD. REV. SEE TA		SCALE: None	SIZE:	SHEET: 1 of 1	